# MSKSEMI 美森科













ESD

MOV

GDT

PIFD

2SC2873-x-MS

Product specification





## TRANSISTOR (NPN)

#### **FEATURE**

- Small Flat Package
- High Speed Switching Time
- Low Collector-emitter saturation voltage
- Complementary to 2SA1213-x-MS

## **Reference News**

# **SOT-89**

- 1. BASE
- 2. COLLECTOR 3. EMITTER

#### **MARKING**

2SC2873-O-MS	2SC2873-Y-MS	
MO	MY	

## MAXIMUM RATINGS (Ta=25℃ unless otherwise noted)

Symbol	Parameter	Value	Unit
V <sub>CBO</sub>	Collector-Base Voltage	50	V
V <sub>CEO</sub>	Collector-Emitter Voltage	50	V
V <sub>EBO</sub>	Emitter-Base Voltage	5	V
Ic	Collector Current	2	А
Pc	Collector Power Dissipation	500	mW
Reja	Thermal Resistance From Junction To Ambient	250	°C/W
Tj	Junction Temperature	150	$^{\circ}$
T <sub>stg</sub>	Storage Temperature	-55~+150	$^{\circ}$



# **ELECTRICAL CHARACTERISTICS (T₂=25℃ unless otherwise specified)**

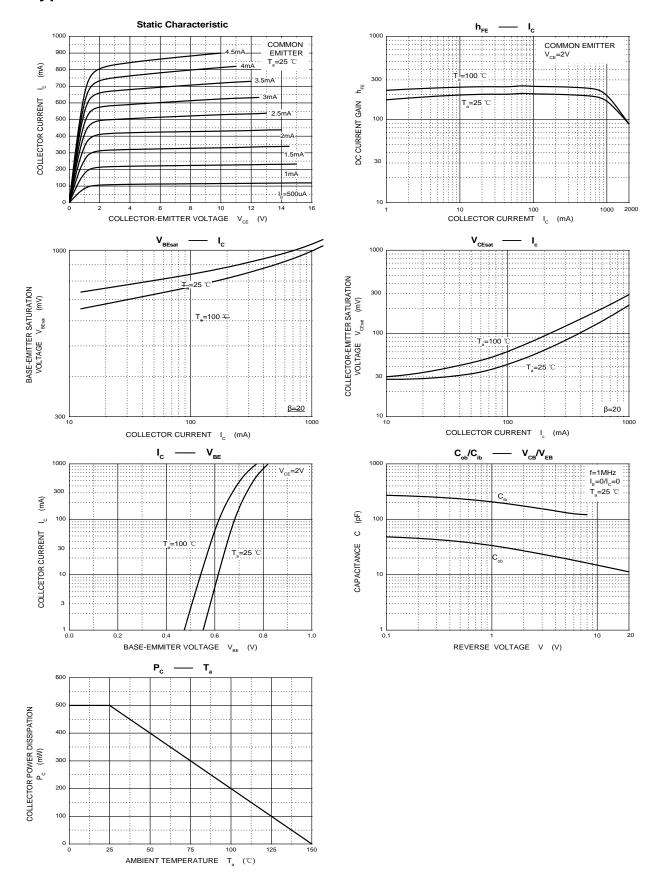
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	lc=100μA,I <sub>E</sub> =0	50			V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> =1mA,I <sub>B</sub> =0	50			V
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> =100μA,I <sub>C</sub> =0	5			V
Collector cut-off current	Ісво	V <sub>CB</sub> =50V,I <sub>E</sub> =0			0.1	μA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> =5V,I <sub>C</sub> =0			0.1	μA
DC current gain	h <sub>FE(1)</sub>	V <sub>CE</sub> =2V, I <sub>C</sub> =0.5A	70		240	
Do santin gain	h <sub>FE(2)</sub>	V <sub>CE</sub> =2V, I <sub>C</sub> =2A	20			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =1A,I <sub>B</sub> =50mA			0.5	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	I <sub>C</sub> =1A,I <sub>B</sub> =50mA			1.2	V
Transition frequency	f⊤	Vce=2V,Ic=0.5A		120		MHz
Collector output capacitance	Cob	V <sub>CB</sub> =10V, I <sub>E</sub> =0, f=1MHz		30		рF

## CLASSIFICATION OF hFE

Rank	2SC2873-O-MS	2SC2873-Y-MS
Range	70 -140	120–240

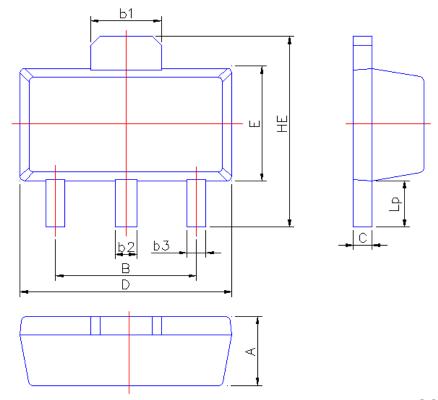


## **Typical Characteristics**





## PACKAGE MECHANICAL DATA



**SOT-89** 

	Dimension in Millimeters		
Symbol	Min	Max	
А	1.40	1.60	
В	2.95	3.05	
b1	1.45	1.70	
b2	0.45	0.60	
b3	0.35	0.50	
С	0.35	0.50	
D	4.40	4.60	
E	2.35	2.55	
HE	3.90	4.40	
Lp	0.90	1.10	

## **REELSPECIFICATION**

P/N	PKG	QTY
2SC2873-x-MS	SOT-89	1000



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